

PTDCS40120BY

1200V 40A Si IGBT Discrete



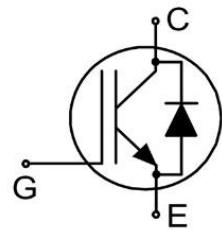
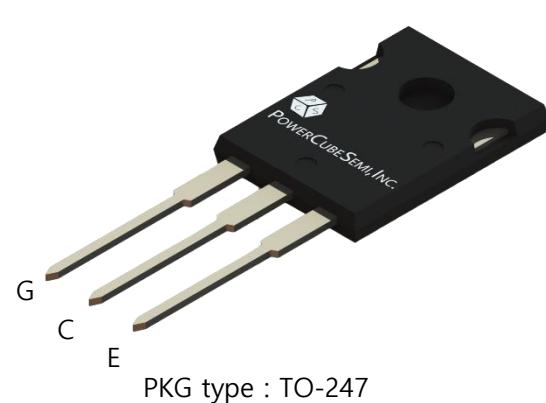
Features

Si IGBT Discrete

- Rated to 1200V at 40Amps @ $T_J = 25^\circ\text{C}$
- $V_{CE(\text{sat})}=1.85\text{V}$ @ $I_C=40\text{A}$
- High Breakdown voltage to 1200V for improved reliability
- Maximum junction temperature 175°C
- Positive temperature coefficient
- Including fast & soft recovery anti-parallel FWD

Application

- High frequency Switching
- Resonant Converters
- Uninterruptible power supply
- Welding Converters



Absolute Maximum Ratings

Symbol	Parameter		Value	Unit
BV_{CES}	Collector-Emitter Breakdown Voltage		1200	V
I_C	DC Collector Current	$T_C=25^\circ\text{C}$	80	A
		$T_C=100^\circ\text{C}$	40	
$I_{C,\text{Pulse}}$	Pulsed Collector Current		160	A
I_F	Diode Forward Current	$T_C=25^\circ\text{C}$	80	A
		$T_C=100^\circ\text{C}$	40	
$I_{F,\text{Pulse}}$	Diode Pulsed Current		160	A
V_{GE}	Continuous Gate-Emitter Voltage		± 20	V
V_{GE}	Transient Gate-Emitter Voltage		± 30	
P_D	Power Dissipation	$T_C=25^\circ\text{C}$	375	W
T_{vj}	Operating Junction Temperature Range		-40 to 175	$^\circ\text{C}$
T_{stg}	Storage Temperature Range		-55 to 150	



Package Marking and Ordering Information

Device Marking	Device	Package	Packing Method	Tape width	Quantity
PTDCS40120BY	PTDCS40120	TO-247	TUBE	-	30

Electrical Characteristics

$T_j=25^\circ\text{C}$ Unless Otherwise Specified

Static Characteristics

Symbol	Parameter	Test Condition	Numerical			Unit
			Min	Typ	Max	
BV_{CES}	Collector-Emitter Breakdown Voltage	$I_C=250\mu\text{A}, V_{\text{GE}}=0\text{V}$	1200	-	-	V
$V_{\text{CE}(\text{sat})}$	Collector-Emitter Saturation Voltage	$I_C=40\text{A}, V_{\text{GE}}=15\text{V}$	$T_j=25^\circ\text{C}$	-	1.85	2.15
			$T_j=125^\circ\text{C}$	-	2.15	-
			$T_j=150^\circ\text{C}$	-	2.25	-
$V_{\text{GE}(\text{TH})}$	Gate-Emitter Threshold Voltage	$V_{\text{CE}}=V_{\text{GE}}, I_C=1.4\text{mA}$	5.2	5.8	6.5	V
I_{CES}	Zero Gate Voltage Collector Current	$V_{\text{CE}}=1200\text{V}, V_{\text{GE}}=0\text{V}$	$T_j=25^\circ\text{C}$	-	-	0.25
			$T_j=150^\circ\text{C}$	-	-	4
I_{GES}	Gate-Emitter Leakage Current	$V_{\text{GE}}=\pm 20\text{V}, V_{\text{CE}}=0\text{V}$	-	-	100	nA

Dynamic Characteristics

Symbol	Parameter	Test Condition	Numerical			Unit
			Min	Typ	Max	
Q_G	Total Gate Charge	$V_{\text{CC}}=600\text{V}, I_C=40\text{A}, V_{\text{GE}}=15\text{V}$	-	0.27	-	uC
V_F	Diode Forward Voltage	$I_F=40\text{A}$	$T_j=25^\circ\text{C}$	-	2.05	2.70
			$T_j=125^\circ\text{C}$	-	1.85	-
			$T_j=150^\circ\text{C}$	-	1.75	-
C_{IES}	Input Capacitance	$V_{\text{CE}}=25\text{V}, V_{\text{GE}}=0\text{V}, f=1\text{MHz}$	-	5.52	-	nF
C_{RES}	Reverse Transfer Capacitance		-	0.05	-	



Electrical Characteristics

T_j=25°C Unless Otherwise Specified

Switching Characteristics

Symbol	Parameter	Test Condition	Numerical			Unit
			Min	Typ	Max	
t _{d(on)}	Turn-On Delay Time	V _{GE} =-5~15V, V _{CC} =600V, I _C =40A, R _G =20Ω	T _j =25°C	-	60	-
t _r	Turn-On Rise Time			-	52	-
t _{d(off)}	Turn-Off Delay Time			-	49	-
t _f	Turn-Off Fall Time		T _j =125°C	-	106	-
E _{on}	Turn-On Switching Energy			-	94	-
E _{off}	Turn-Off Switching Energy			-	87	-
E _{rec}	Reverse Recovery Energy		T _j =150°C	-	200	-
I _{rr}	Reverse Recovery Current			-	210	-
Q _{rr}	Reverse Recovery Charge			-	223	-
T _{rr}	Reverse Recovery Time			-	129	-
				-	187	-
				-	210	-
				-	5.13	-
				-	5.18	-
				-	5.24	-
				-	1.38	-
				-	2.02	-
				-	2.23	-
				-	0.36	-
				-	1.10	-
				-	1.26	-
				-	11	-
				-	14	-
				-	16	-
				-	1.43	-
				-	3.58	-
				-	4.25	-
				-	229	-
				-	307	-
				-	352	-

Thermal Characteristics

Symbol	Parameter	Numerical	Unit
R _{θ(J-A)}	Thermal Resistance Junction-to-Ambient	40	K/W
R _{θ(J-C)}	Thermal Resistance Junction-to-Case for IGBT	0.40	
R _{θ(J-C)}	Thermal Resistance Junction-to-Case for Diode	0.65	

Typical Characteristics

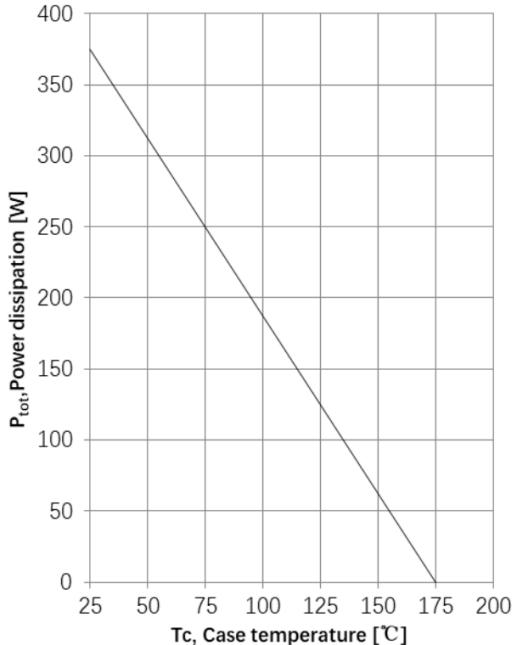


Figure 1. Power dissipation as a function of case temperature ($T_J \leq 175^\circ\text{C}$)

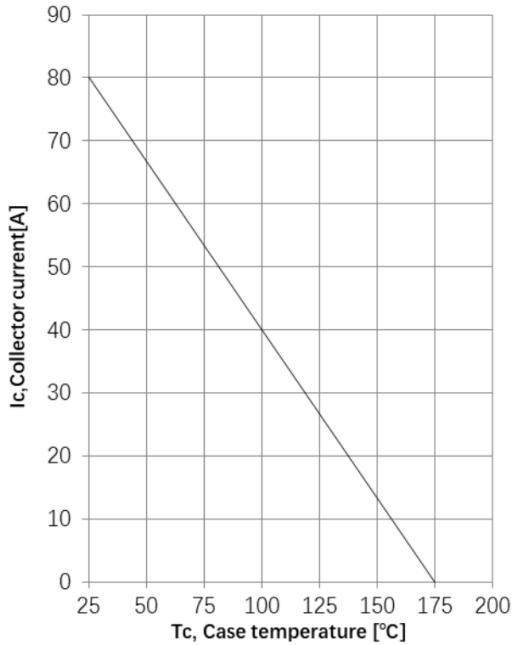


Figure 2. Collector current as a function of case temperature ($V_{GE} \geq 15\text{V}$, $T_J \leq 175^\circ\text{C}$)

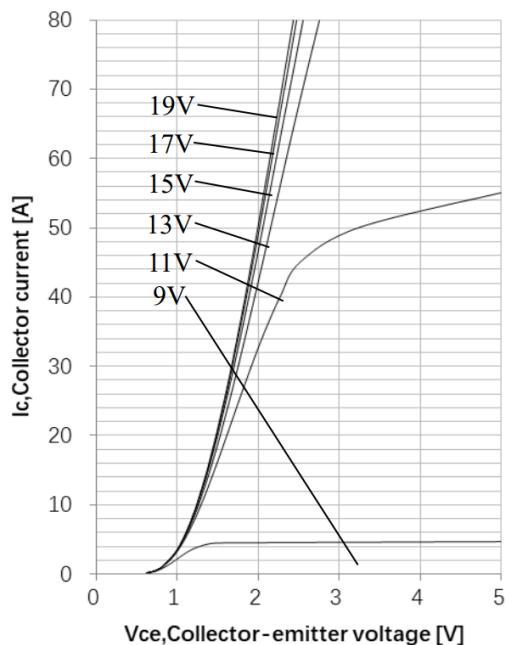


Figure 3. Typical output Characteristics ($T_J=25^\circ\text{C}$)

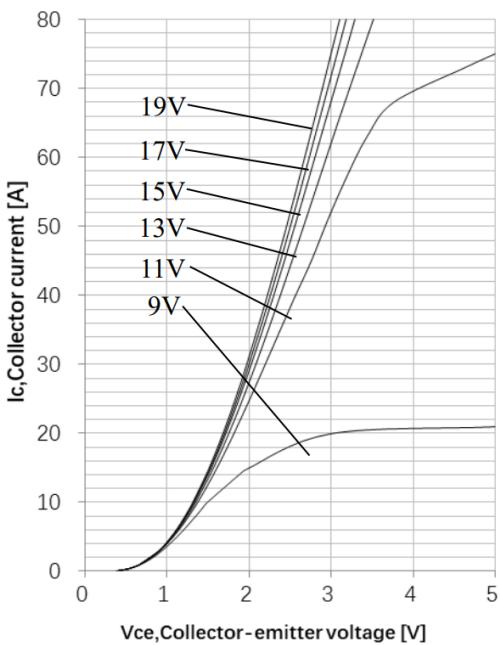


Figure 4. Typical output Characteristics ($T_J=150^\circ\text{C}$)

Typical Characteristics

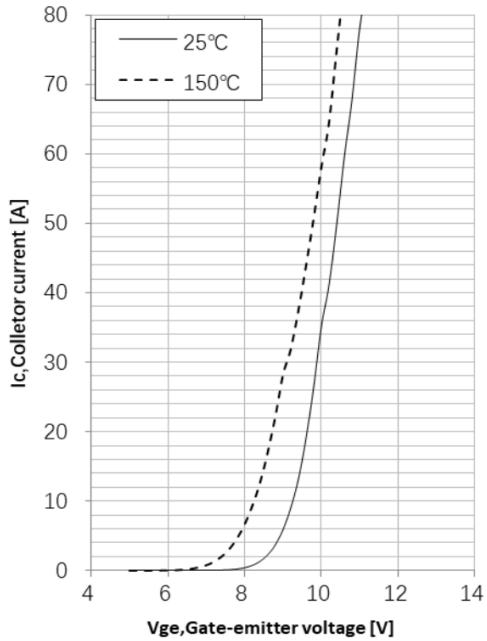


Figure 5. Typical transfer characteristics ($V_{CE}=20\text{V}$)

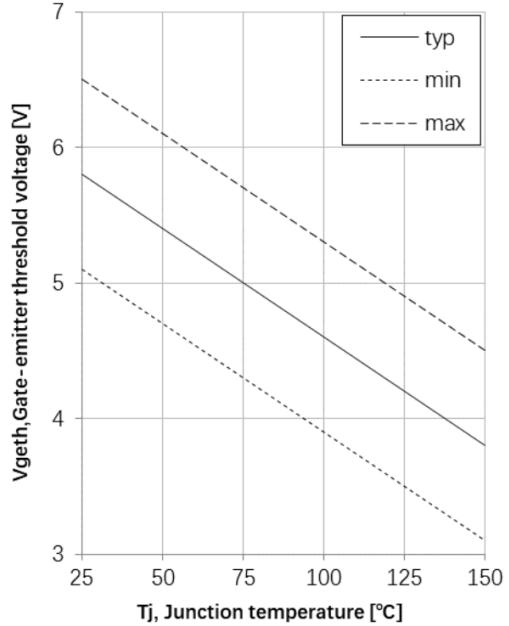


Figure 6. Gate-Emitter threshold voltage as a function of junction temperature

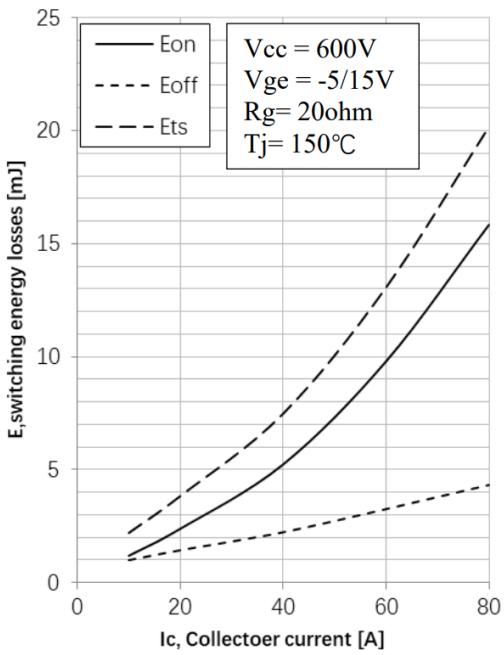


Figure 7. Typical Switching Energy losses as a function of collect current

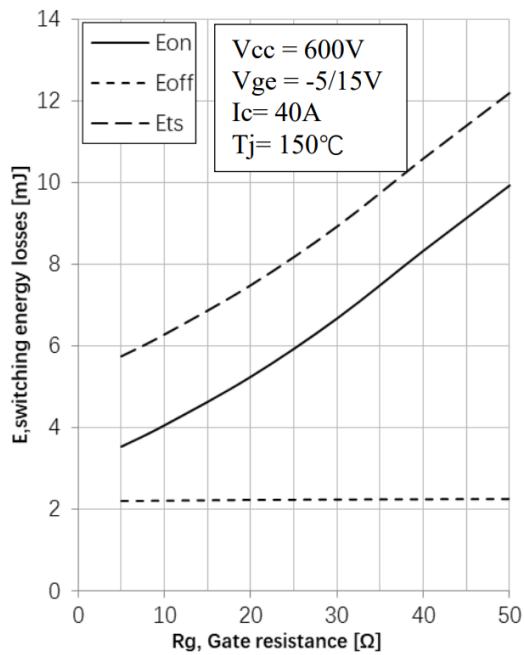


Figure 8. Typical Switching Energy losses as a function of gate resistance

Typical Characteristics

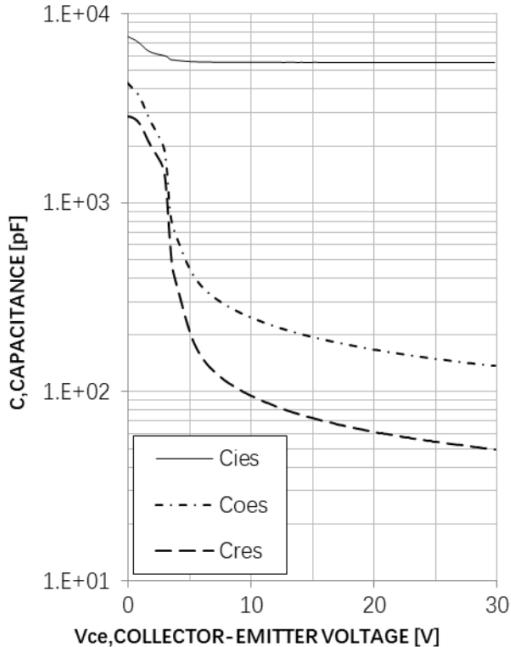


Figure 9. Typical Capacitance as a function of collector-emitter voltage

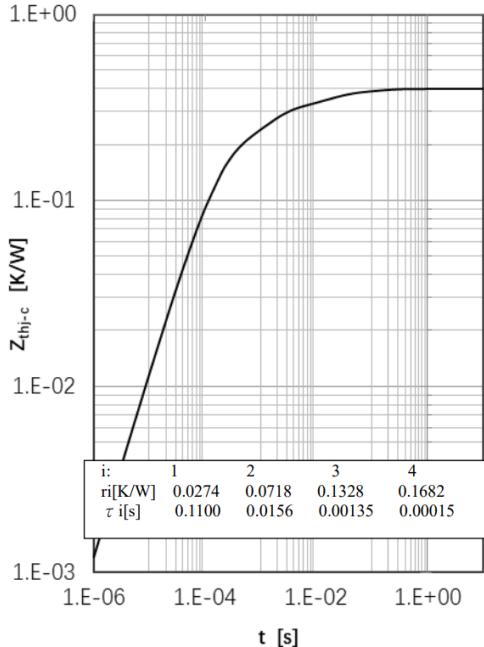


Figure 10. IGBT Transient Thermal Impedance

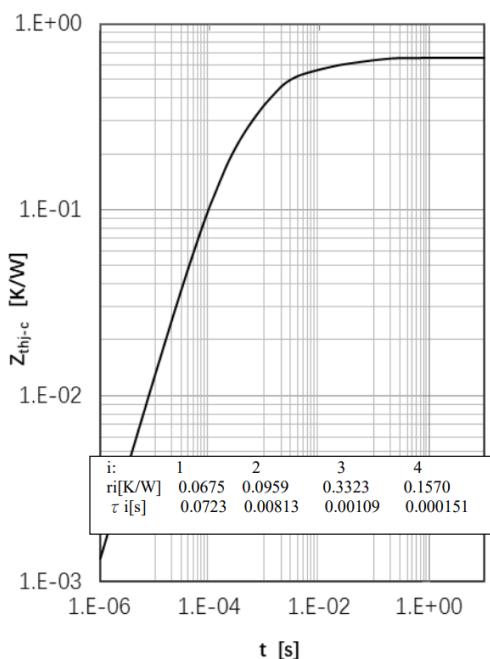


Figure 11. Diode Transient Thermal Impedance

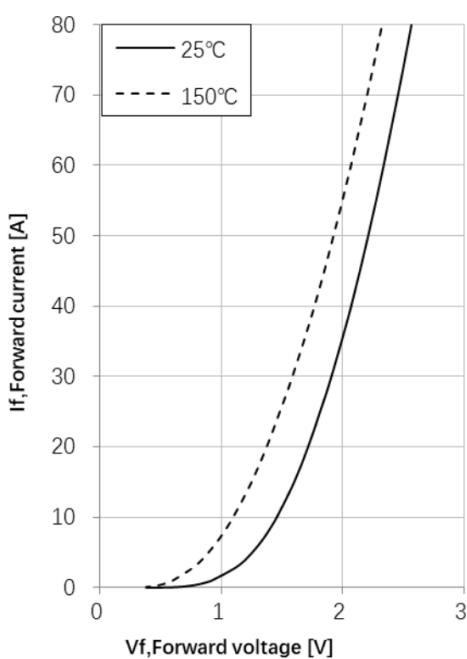
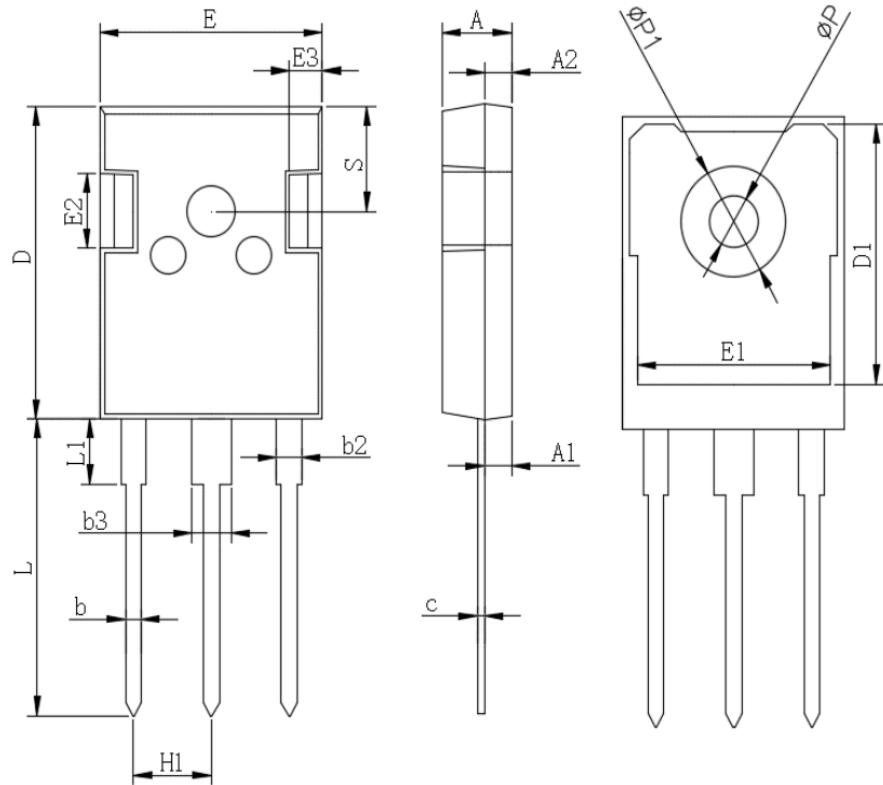


Figure 12. Diode forward current as a function of forward voltage



Package Outline



Unit : mm

SYMBOL	DIMENSIONS	
	MIN	MAX
A	4.80	5.20
A1	2.21	2.61
A2	1.85	2.15
b	1.0	1.4
b2	1.91	2.21
C	0.5	0.7
D	20.70	21.30
D1	16.25	16.85
E	15.50	16.10
E1	13.0	13.6
E2	4.80	5.20
E3	2.30	2.70
L	19.62	20.22
L1	-	4.30
ΦP	3.40	3.80
ΦP1	-	7.30
S	6.15 Typ	
H1	5.44 Typ	
b3	2.80	3.20